



ABSTRACT OF THE DISCLOSURE

An imaging apparatus is formed of two or more imaging subarrays. Each imaging subarray is formed of a printed wiring board containing semiconductor imaging chips. The end chip of each board projects beyond the edge of the board. The imaging subarrays are joined together so that the projecting end chips may be closely spaced from one and another, without the circuit boards contacting one another. Glass tie bars formed of a low thermal expansion glass secure the boards to one another. A light curable adhesive secures each tie bar to the printed wiring board.

[illegible]